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**UPDATE CHANGE NOTIFICATION**Generic Copy

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**16 Nov 2007****SUBJECT: ON Semiconductor Update Notification #16066****TITLE: Removal of specified devices from original device list for IPCN #16055 – Capacity Expansion for Devices Fabricated at XFAB Wafer Foundries****PROPOSED FIRST SHIP DATE: 16 Nov 2007****AFFECTED CHANGE CATEGORY(S): Wafer Fab****AFFECTED PRODUCT DIVISION(S): ECL Products (PJ)****ADDITIONAL RELIABILITY DATA: N/A****SAMPLES: N/A****FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or John Veto <[john.veto@onsemi.com](mailto:john.veto@onsemi.com)>**NOTIFICATION TYPE:**

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

ON Semiconductor would like to issue this update notification to notify our customers that the attached list of parts are being removed from the original device list that was published on IPCN #16055 issued on 01 Oct. 2007. These devices will not be transferring to any XFAB facilities as initially indicated.

For questions or concerns regarding this update notification, please contact John Veto at 602-244-5699 <[john.veto@onsemi.com](mailto:john.veto@onsemi.com)> or Prescott Sakai at 602-244-3543 <[prescott.sakai@onsemi.com](mailto:prescott.sakai@onsemi.com)>



**Update Notification #16066**

**AFFECTED DEVICE LIST**

NB3L553DG  
NB3L553MNR4G  
NB3L553MNR4G  
NB3N2304NZDTG  
NB3N2304NZDTR2G  
NB3N2304NZMNR4G  
NB3N502DG  
NB3N502DR2G  
NB3N551DG  
NB3N551DR2G